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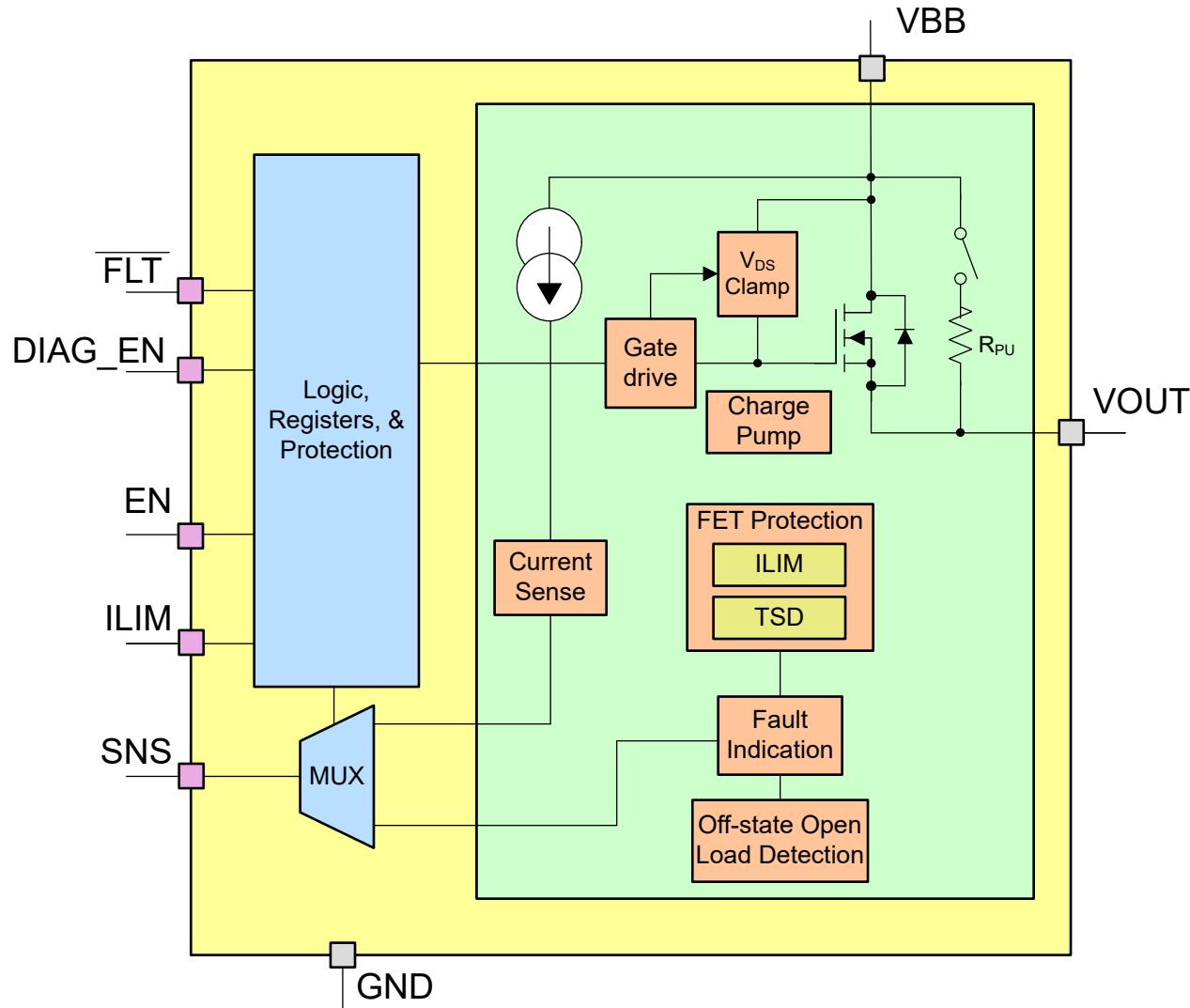
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## 1 Overview

This document contains information for TPS1HC08-Q1 (VAH (QFN, 11) package) to aid in a functional safety system design. Information provided are:

- Functional safety failure in time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and distribution (FMD) based on the primary function of the device
- Pin failure mode analysis (Pin FMA)

Figure 1-1 shows the device functional block diagram for reference.



**Figure 1-1. Functional Block Diagram**

The TPS1HC08-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

## 2 Functional Safety Failure In Time (FIT) Rates

This section provides functional safety failure in time (FIT) rates for TPS1HC08-Q1 based on two different industry-wide used reliability standards:

- [Table 2-1](#) provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- [Table 2-2](#) provides FIT rates based on the Siemens Norm SN 29500-2

**Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11**

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10 <sup>9</sup> Hours)
Total component FIT rate	12
Die FIT rate	6
Package FIT rate	6

The failure rate and mission profile information in [Table 2-1](#) comes from the reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission profile: Motor control from table 11 or figure 16
- Power dissipation: 750mW
- Climate type: World-wide table 8 or figure 13
- Package factor (lambda 3): Table 17b or figure 15
- Substrate material: FR4
- EOS FIT rate assumed: 0 FIT

**Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2**

Table	Category	Reference FIT Rate	Reference Virtual T <sub>J</sub>
5	CMOS, BICMOS Digital, analog, or mixed	25 FIT	55°C

The reference FIT rate and reference virtual T<sub>J</sub> (junction temperature) in [Table 2-2](#) come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

### 3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for TPS1HC08-Q1 in [Table 3-1](#) comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity, and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures resulting from misuse or overstress.

**Table 3-1. Die Failure Modes and Distribution**

Die Failure Modes	Failure Mode Distribution (%)
VOUT open (Hi-Z)	20
VOUT stuck ON to VBB	10
VOUT functional – not in specification voltage or timing	50
Diagnostics not in specification	10
Protection function fails to trip	10

## 4 Pin Failure Mode Analysis (Pin FMA)

This section provides a failure mode analysis (FMA) for the pins of the TPS1HC08-Q1. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

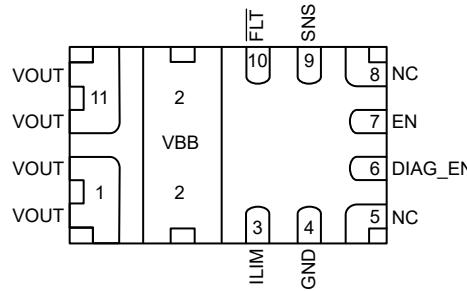
- Pin short-circuited to ground (see [Table 4-2](#))
- Pin open-circuited (see [Table 4-3](#))
- Pin short-circuited to an adjacent pin (see [Table 4-4](#))
- Pin short-circuited to VS supply (see [Table 4-5](#))

[Table 4-2](#) through [Table 4-5](#) also indicate how these pin conditions can affect the device as per the failure effects classification in [Table 4-1](#).

**Table 4-1. TI Classification of Failure Effects**

Class	Failure Effects
A	Potential device damage that affects functionality.
B	No device damage, but loss of functionality.
C	No device damage, but performance degradation.
D	No device damage, no impact to functionality or performance.

[Figure 4-1](#) shows the TPS1HC08-Q1 pin diagram. For a detailed description of the device pins please refer to the *Pin Configuration and Functions* section in the TPS1HC08-Q1 datasheet.



**Figure 4-1. Pin Diagram for VAH (QFN, 11)**

Following are the assumptions of use and the device configuration assumed for the pin FMA in this section:

- The device pins are connected per the recommendation in the datasheet, including pullup and pulldown resistors, as needed.
- The datasheet recommendations for operating conditions, external component selection, and PCB layout are followed.

**Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground**

Pin Name	Pin No.	Description of Potential Failure Effects	Failure Effect Class
VOUT	1	The current limit of the device engages, and thermal protection turns off the FET.	B
	11		
VBB	2	The output stages are not powered, and the FET does not turn ON.	B
ILIM	3	The current limit is set at a maximum level, as per the datasheet.	C
GND	4	Any GND network, connected for protection, is bypassed.	B
NC	5	There is no effect on the device.	D
	8		
DIAG_EN	6	The diagnostic features do not function, including current sense and fault reporting.	B

**Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground (continued)**

Pin Name	Pin No.	Description of Potential Failure Effects	Failure Effect Class
EN	7	The FET is turned off and reports an erroneous open-load fault for no-load conditions when the DIAG_EN pin is high.	B
SNS	9	The reported SNS current or fault status on the SNS pin is erroneous.	B
FLT	10	The reported fault status is potentially erroneous.	B

**Table 4-3. Pin FMA for Device Pins Open-Circuited**

Pin Name	Pin No.	Description of Potential Failure Effects	Failure Effect Class
VOUT	1	During the ON state of the device, FET is disconnected. During the OFF state of the device, if the DIAG_EN pin is high, an open-load fault reports.	B
	11	DIAG_EN pin is high, an open-load fault reports.	
VBB	2	The device is not powered and the FET is kept OFF.	B
ILIM	3	The current limit is set at a minimum level, as per the datasheet.	C
GND	4	The loss of ground detection engages, and the device turns OFF.	B
NC	5	There is no effect on the device.	D
	8	There is no effect on the device.	
DIAG_EN	6	The diagnostic features do not function, including current sense and fault reporting. (internal pulldown).	B
EN	7	The FET is turned off and reports an erroneous open-load fault for no-load conditions when the DIAG_EN pin is high. (internal pulldown).	B
SNS	9	The current sense and fault at the SNS pin is not reported.	B
FLT	10	The fault condition is not reported.	B

**Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin**

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effects	Failure Effect Class
VOUT	1	VBB	The output is pulled to supply voltage. A short-to-battery detection triggers during the OFF state if the DIAG_EN pin is high.	B
	11			
ILIM	3	VBB	There is a loss of the current limit setting based on the RLIM resistor.	C
GND	4	ILIM	The current limit is set at a maximum level, as per the datasheet.	C
NC	5	GND	There is no effect on the device.	D
DIAG_EN	6	NC	There is no effect on the device.	D
EN	7	DIAG_EN	Loss of enable control and open-load fault detection is erroneous when the DIAG_EN pin is high.	B
NC	8	EN	There is no effect on the device.	D
SNS	9	NC	There is no effect on the device.	D
FLT	10	SNS	The reported fault status and voltage of the SNS pin is potentially erroneous.	B
VBB	2	FLT	The reported fault status is potentially erroneous.	B

**Table 4-5. Pin FMA for Device Pins Short-Circuited to VBB Supply**

Pin Name	Pin No.	Description of Potential Failure Effects	Failure Effect Class
VOUT	1	The output of FET is pulled to the supply voltage. A short-to-battery detection triggers during the OFF state if the DIAG_EN pin is high.	B
	11		
VBB	2	There is no effect on the device.	D
ILIM	3	There is a loss of the current limit setting based on the RLIM resistor.	C
GND	4	The supply power is bypassed, and the device stays OFF.	B
NC	5	There is no effect on the device.	D
	8		
DIAG_EN	6	There is a potential violation of the absolute maximum rating for the pin and a possible breakdown of the ESD cell.	A
EN	7	There is a potential violation of the absolute maximum rating for the pin and a possible breakdown of the ESD cell.	A
SNS	9	There is a potential violation of the absolute maximum rating for the pin and a possible breakdown of the ESD cell.	A
FLT	10	The reported fault status is potentially erroneous.	B

## 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
December 2025	*	Initial Release

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